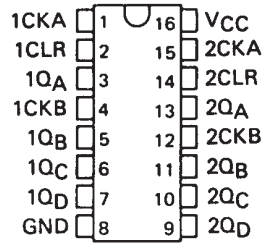
- Dual Versions of the Popular '90A, 'LS90 and '93A, 'LS93
- '390, 'LS390 . . . Individual Clocks for A and B Flip-Flops Provide Dual ÷ 2 and ÷ 5 Counters
- '393, 'LS393 . . . Dual 4-Bit Binary Counter with Individual Clocks
- All Have Direct Clear for Each 4-Bit Counter
- Dual 4-Bit Versions Can Significantly Improve System Densities by Reducing Counter Package Count by 50%
- Typical Maximum Count Frequency . . . 35 MHz
- Buffered Outputs Reduce Possibility of Collector Commutation

description

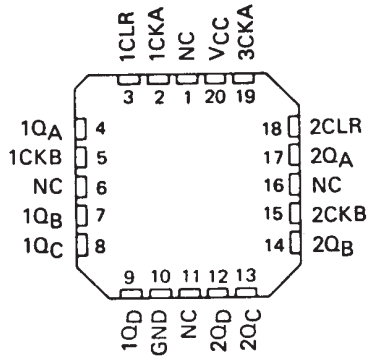
Each of these monolithic circuits contains eight master-slave flip-flops and additional gating to implement two individual four-bit counters in a single package. The '390 and 'LS390 incorporate dual divide-by-two and divide-by-five counters, which can be used to implement cycle lengths equal to any whole and/or cumulative multiples of 2 and/or 5 up to divide-by-100. When connected as a bi-quinary counter, the separate divide-by-two circuit can be used to provide symmetry (a square wave) at the final output stage. The '393 and 'LS393 each comprise two independent four-bit binary counters each having a clear and a clock input. N-bit binary counters can be implemented with each package providing the capability of divide-by-256. The '390, 'LS390, '393, and 'LS393 have parallel outputs from each counter stage so that any submultiple of the input count frequency is available for system-timing signals.

Series 54 and Series 54LS circuits are characterized for operation over the full military temperature range of −55°C to 125°C; Series 74 and Series 74LS circuits are characterized for operation from 0°C to 70°C.

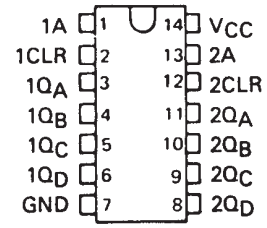
SN54390, SN54LS390 . . . J OR W PACKAGE
SN74390 . . . N PACKAGE
SN74LS390 . . . D OR N PACKAGE
(TOP VIEW)



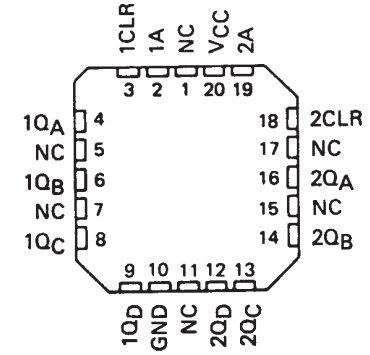
SN54LS390 . . . FK PACKAGE
(TOP VIEW)



SN54393, SN54LS393 . . . J OR W PACKAGE
SN74393 . . . N PACKAGE
SN74LS393 . . . D OR N PACKAGE
(TOP VIEW)



SN54LS393 . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection

FUNCTION TABLES

'390, 'LS390 BCD COUNT SEQUENCE (EACH COUNTER) (See Note A)

COUNT	OUTPUT			
	Q_D	Q_C	Q_B	Q_A
0	L	L	L	L
1	L	L	L	H
2	L	L	H	L
3	L	L	H	H
4	L	H	L	L
5	L	H	L	H
6	L	H	H	L
7	L	H	H	H
8	H	L	L	L
9	H	L	L	H

'390, 'LS390 BI-QUINARY (5-2) (EACH COUNTER) (See Note B)

COUNT	OUTPUT			
	Q_A	Q_D	Q_C	Q_B
0	L	L	L	L
1	L	L	L	H
2	L	L	H	L
3	L	L	H	H
4	L	H	L	L
5	H	L	L	L
6	H	L	L	H
7	H	L	H	L
8	H	L	H	H
9	H	H	L	L

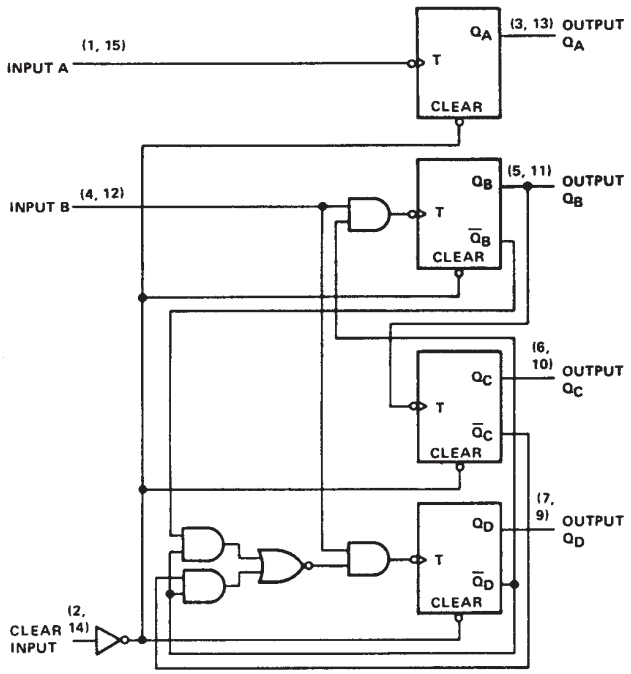
'393, 'LS393 COUNT SEQUENCE (EACH COUNTER)

COUNT	OUTPUT			
	Q_D	Q_C	Q_B	Q_A
0	L	L	L	L
1	L	L	L	H
2	L	L	H	L
3	L	L	H	H
4	L	H	L	L
5	L	H	L	H
6	L	H	H	L
7	L	H	H	H
8	H	L	L	L
9	H	L	L	H
10	H	L	H	L
11	H	L	H	H
12	H	H	L	L
13	H	H	L	H
14	H	H	H	L
15	H	H	H	H

NOTES: A. Output Q_A is connected to input B for BCD count.
B. Output Q_D is connected to input A for bi-quinary count.
C. H = high level, L = low level.

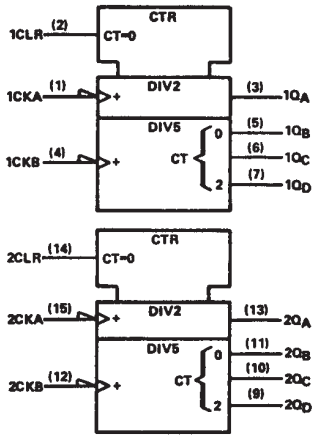
logic diagrams (positive logic)

'390, 'LS390

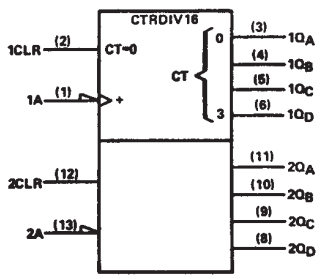


logic symbols†

'390, 'LS390



'393, 'LS393

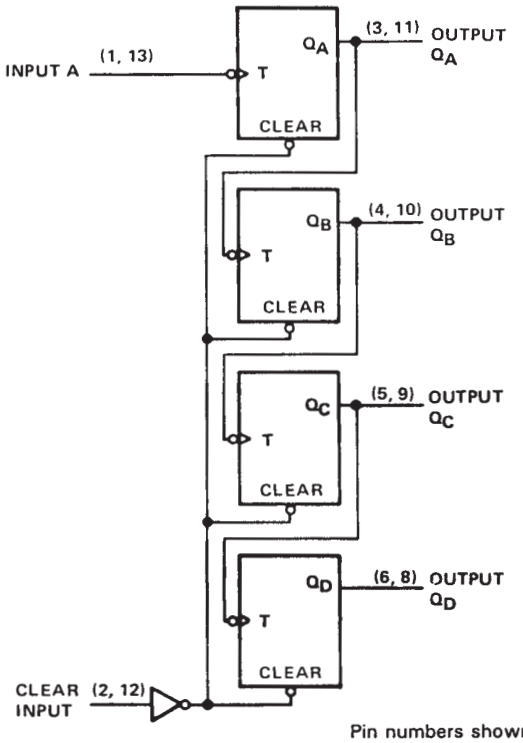


†These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

logic diagrams (continued)

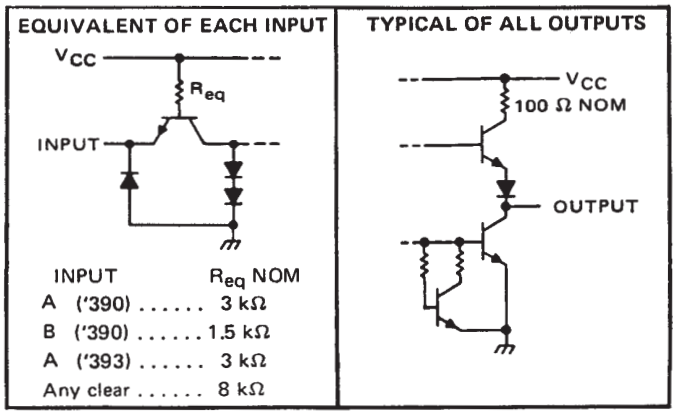
'393, 'LS393



Pin numbers shown are for D, J, N and W packages.

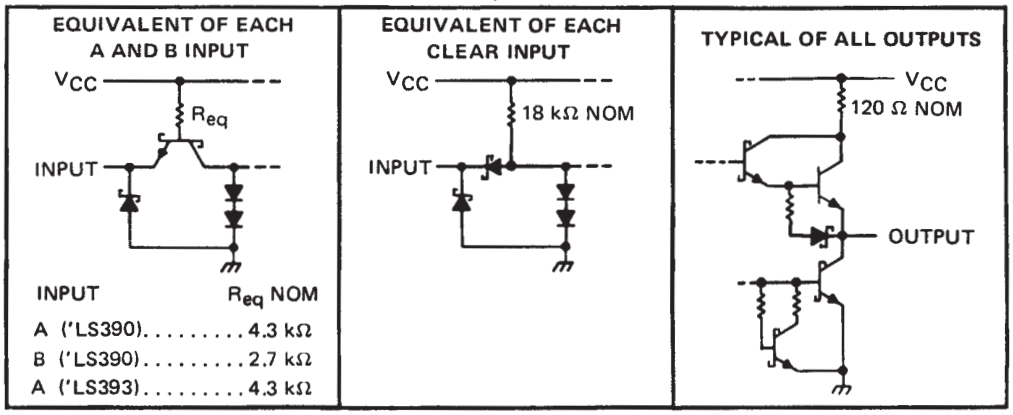
schematics of inputs and outputs

'390, '393



INPUT	R_{eq} NOM
A ('390)	3 kΩ
B ('390)	1.5 kΩ
A ('393)	3 kΩ
Any clear	8 kΩ

'LS390, 'LS393



INPUT	R_{eq} NOM
A ('LS390)	4.3 kΩ
B ('LS390)	2.7 kΩ
A ('LS393)	4.3 kΩ

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 5.5 V
Operating free-air temperature range: SN54390, SN54393 . . . . . −55°C to 125°C
SN74390, SN74393 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54390 SN54393			SN74390 SN74393			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}				−800			−800	μA
Low-level output current, I_{OL}				16			16	mA
Count frequency, f_{count}	A input	0		25	0		25	MHz
	B input	0		20	0		20	
Pulse width, t_w	A input high or low	20			20			ns
	B input high or low	25			25			
	Clear high	20			20			
Clear inactive-state setup time, t_{su}		25↓			25↓			ns
Operating free-air temperature, T_A		−55		125	0		70	°C

↓ The arrow indicates that the falling edge of the clock pulse is used for reference.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†		'390 MIN	'390 TYP‡	'390 MAX	'393 MIN	'393 TYP‡	'393 MAX	UNIT
V_{IH}	High-level input voltage				2			2			V
V_{IL}	Low-level input voltage						0.8			0.8	V
V_{IK}	Input clamp voltage		V_{CC} = MIN, I_I = −12 mA				−1.5			−1.5	V
V_{OH}	High-level output voltage		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OH} = −800 μA		2.4	3.4		2.4	3.4		V
V_{OL}	Low-level output voltage		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OL} = 16 mA¶			0.2	0.4		0.2	0.4	V
I_I	Input current at maximum input voltage		V_{CC} = MAX, V_I = 5.5 V				1			1	mA
I_{IH}	High-level input current	Clear	V_{CC} = MAX, V_I = 2.4 V				40			40	μA
		Input A					80			80	
		Input B					120				
I_{IL}	Low-level input current	Clear	V_{CC} = MAX, V_I = 0.4 V				−1			−1	mA
		Input A					−3.2			−3.2	
		Input B					−4.8				
I_{OS}	Short-circuit output current§		V_{CC} = MAX	SN54'	−20		−57	−20		−57	mA
				SN74'	−18		−57	−18		−57	
I_{CC}	Supply current		V_{CC} = MAX, See Note 2			42	69		38	64	mA

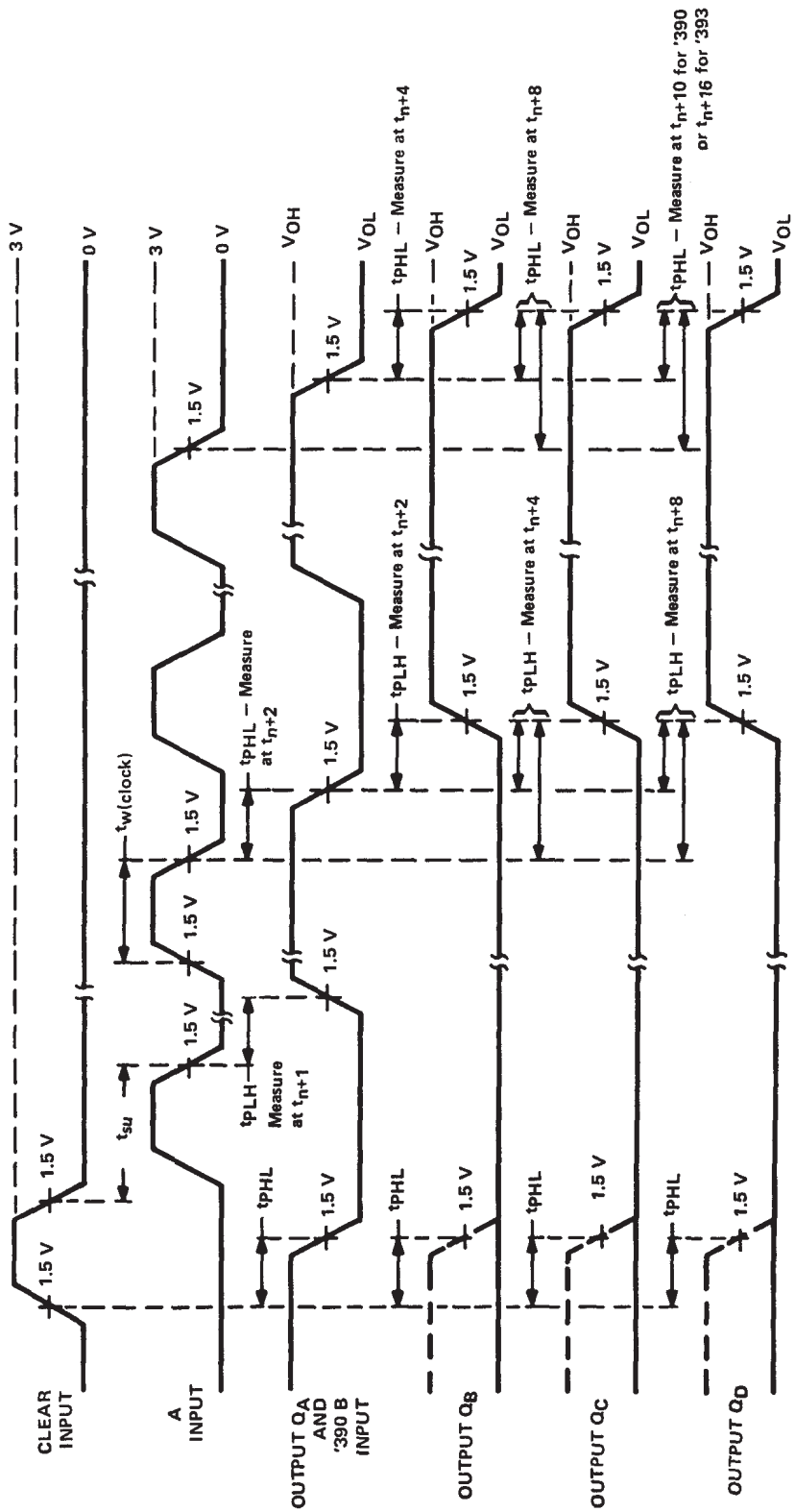
† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time.
¶ The Q_A outputs of the '390 are tested at I_{OL} = 16 mA plus the limit value for I_{IL} for the B input. This permits driving the B input while maintaining full fan-out capability.
NOTE 2: I_{CC} is measured with all outputs open, both clear inputs grounded following momentary connection to 4.5 V, and all other inputs grounded.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'390			'393			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
f_{max}	A	Q_A	C_L = 15 pF, R_L = 400 Ω, See Note 3 and Figure 1	25	35		25	35		MHz
	B	Q_B		20	30					
t_{PLH}	A	Q_A			12	20		12	20	ns
t_{PHL}					13	20		13	20	
t_{PLH}	A	Q_C of '390 Q_D of '393			37	60		40	60	ns
t_{PHL}					39	60		40	60	
t_{PLH}	B	Q_B			13	21				ns
t_{PHL}					14	21				
t_{PLH}	B	Q_C			24	39				ns
t_{PHL}					26	39				
t_{PLH}	B	Q_D			13	21				ns
t_{PHL}					14	21				
t_{PHL}	Clear	Any			24	39		24	39	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

PARAMETER MEASUREMENT INFORMATION



NOTE A: Input pulses are supplied by a generator having the following characteristics $t_r \leq 5$ ns, $t_f \leq 5$ ns, PRR = 1 MHz, duty cycle = 50%, $Z_{out} \approx 50$ ohms.

FIGURE 1

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Clear input voltage . . . . . 7 V
Any A or B clock input voltage . . . . . 5.5 V
Operating free-air temperature range: SN54LS390, SN54LS393 . . . . . −55°C to 125°C
SN74LS390, SN74LS393 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54LS390 SN54LS393			SN74LS390 SN74LS393			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}				−400			−400	μA
Low-level output current, I_{OL}				4			8	mA
Count frequency, f_{count}	A input	0		25	0		25	MHz
	B input	0		12.5	0		12.5	
Pulse width, t_w	A input high or low	20			20			ns
	B input high or low	40			40			
	Clear high	20			20			
Clear inactive-state setup time, t_{su}		25↓			25↓			ns
Operating free-air temperature, T_A		−55		125	0		70	°C

↓ The arrow indicates that the falling edge of the clock pulse is used for reference.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†		SN54LS'			SN74LS'			UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage				2			2			V
V_{IL}	Low-level input voltage						0.7			0.8	V
V_{IK}	Input clamp voltage		V_{CC} = MIN, I_I = −18 mA				−1.5			−1.5	V
V_{OH}	High-level output voltage		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = V_{IL}max, I_{OH} = −400 μA		2.5	3.4		2.7	3.4		V
V_{OL}	Low-level output voltage		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V,	I_{OL} = 4 mA¶		0.25	0.4		0.25	0.4	V
				I_{OL} = 8 mA¶					0.35	0.5	
I_I	Input current at maximum input voltage	Clear	V_{CC} = MAX	V_I = 7 V			0.1			0.1	mA
		Input A		V_I = 5.5 V			0.2			0.2	
		Input B					0.4			0.4	
I_{IH}	High-level input current	Clear	V_{CC} = MAX, V_I = 2.7 V				0.02			0.02	mA
		Input A					0.1			0.1	
		Input B					0.2			0.2	
I_{IL}	Low-level input current	Clear	V_{CC} = MAX, V_I = 0.4 V				−0.4			−0.4	mA
		Input A					−1.6			−1.6	
		Input B					−2.4			−2.4	
I_{OS}	Short-circuit output current§		V_{CC} = MAX		−20		−100	−20		−100	mA
I_{CC}	Supply current		V_{CC} = MAX, See Note 2	'LS390		15	26		15	26	mA
				'LS393		15	26		15	26	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.
¶ The Q_A outputs of the 'LS390 are tested at I_{OL} = MAX plus the limit value for I_{IL} for the clock B input. This permits driving the clock B input while maintaining full fan-out capability.

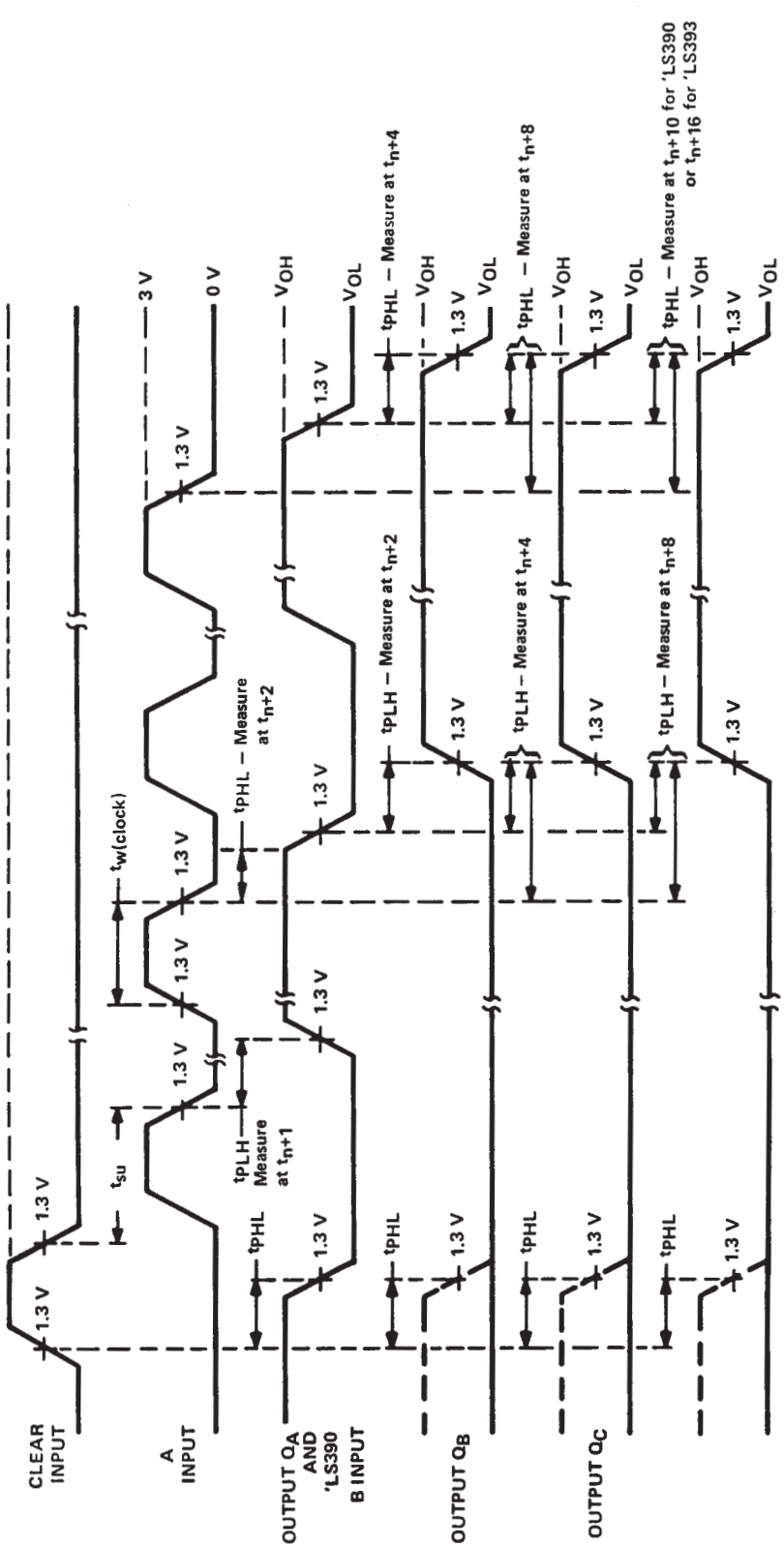
NOTE 2: I_{CC} is measured with all outputs open, both clear inputs grounded following momentary connection to 4.5 V, and all other inputs grounded.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'LS390			'LS393			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
f_{max}	A	Q_A	C_L = 15 pF, R_L = 2 kΩ, See Note 4 and Figure 2	25	35		25	35		MHz
	B	Q_B		12.5	20					
t_{PLH}	A	Q_A			12	20		12	20	ns
t_{PHL}					13	20		13	20	
t_{PLH}	A	Q_C of 'LS390 Q_D of 'LS393			37	60		40	60	ns
t_{PHL}					39	60		40	60	
t_{PLH}	B	Q_B			13	21				ns
t_{PHL}					14	21				
t_{PLH}	B	Q_C			24	39				ns
t_{PHL}					26	39				
t_{PLH}	B	Q_D			13	21				ns
t_{PHL}					14	21				
t_{PHL}	Clear	Any			24	39		24	39	ns

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

PARAMETER MEASUREMENT INFORMATION



VOLTAGE WAVEFORMS

NOTE A: Input pulses are supplied by a generator having the following characteristics $t_r \leq 15$ ns, $t_f \leq 6$ ns, PRR = 1 MHz, duty cycle = 50 %, $Z_{out} \approx 50$ ohms.

FIGURE 2

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
7802601EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601EA SNJ54LS390J	Samples
7802601FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601FA SNJ54LS390W	Samples
7802601FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601FA SNJ54LS390W	Samples
JM38510/32701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32701B2A	Samples
JM38510/32701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32701B2A	Samples
JM38510/32701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32701BEA	Samples
JM38510/32701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32701BEA	Samples
JM38510/32702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32702B2A	Samples
JM38510/32702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32702B2A	Samples
JM38510/32702BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BCA	Samples
JM38510/32702BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BCA	Samples
JM38510/32702BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BDA	Samples
JM38510/32702BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BDA	Samples
JM38510/32702SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702SDA SNV54LS393W	Samples
JM38510/32702SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702SDA SNV54LS393W	Samples
M38510/32701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32701B2A	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
M38510/32701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32701B2A	Samples
M38510/32701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32701BEA	Samples
M38510/32701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32701BEA	Samples
M38510/32702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32702B2A	Samples
M38510/32702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32702B2A	Samples
M38510/32702BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BCA	Samples
M38510/32702BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BCA	Samples
M38510/32702BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BDA	Samples
M38510/32702BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BDA	Samples
M38510/32702SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702SDA SNV54LS393W	Samples
M38510/32702SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702SDA SNV54LS393W	Samples
SN54LS390J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS390J	Samples
SN54LS390J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS390J	Samples
SN54LS393J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS393J	Samples
SN54LS393J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS393J	Samples
SN74LS390D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS390	Samples
SN74LS390D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS390	Samples
SN74LS390DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS390	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS390DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS390	Samples
SN74LS390N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS390N	Samples
SN74LS390N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS390N	Samples
SN74LS390NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS390N	Samples
SN74LS390NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS390N	Samples
SN74LS390NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS390	Samples
SN74LS390NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS390	Samples
SN74LS393D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Samples
SN74LS393D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Samples
SN74LS393DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Samples
SN74LS393DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Samples
SN74LS393DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Samples
SN74LS393DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Samples
SN74LS393N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS393N	Samples
SN74LS393N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS393N	Samples
SN74LS393NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS393N	Samples
SN74LS393NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS393N	Samples
SN74LS393NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS393	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS393NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS393	Samples
SNJ54LS390FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 390FK	Samples
SNJ54LS390FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 390FK	Samples
SNJ54LS390J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601EA SNJ54LS390J	Samples
SNJ54LS390J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601EA SNJ54LS390J	Samples
SNJ54LS390W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601FA SNJ54LS390W	Samples
SNJ54LS390W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601FA SNJ54LS390W	Samples
SNJ54LS393FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 393FK	Samples
SNJ54LS393FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 393FK	Samples
SNJ54LS393J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS393J	Samples
SNJ54LS393J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS393J	Samples
SNJ54LS393W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS393W	Samples
SNJ54LS393W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS393W	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF SN54LS390, SN54LS393, SN54LS393-SP, SN74LS390, SN74LS393 :

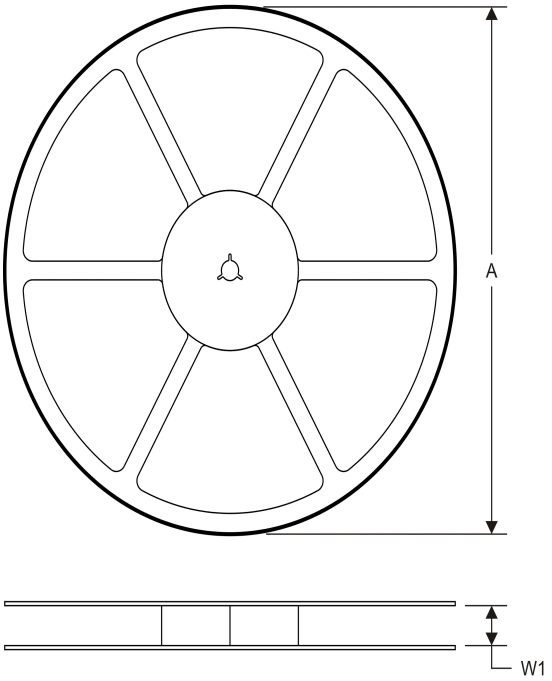
- Catalog: SN74LS390, SN74LS393, SN54LS393
- Military: SN54LS390, SN54LS393
- Space: SN54LS393-SP

NOTE: Qualified Version Definitions:

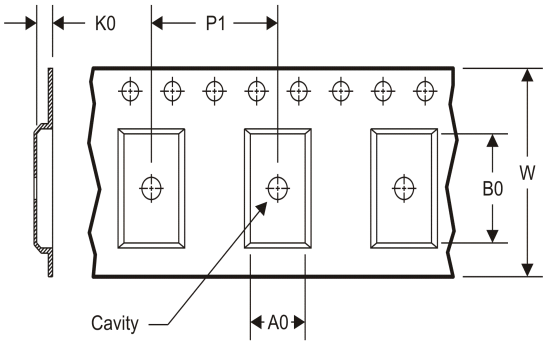
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



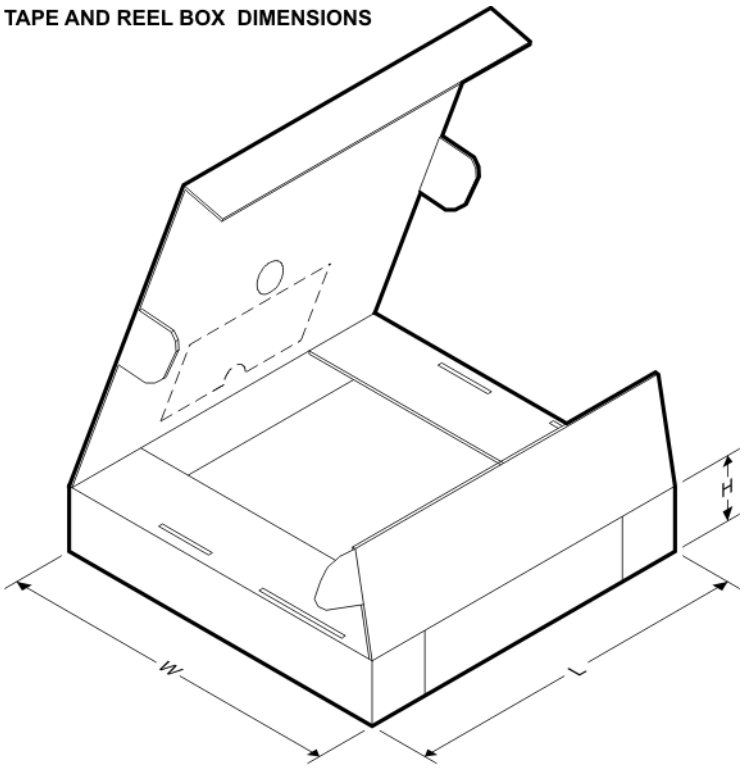
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS390NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS393DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS393NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

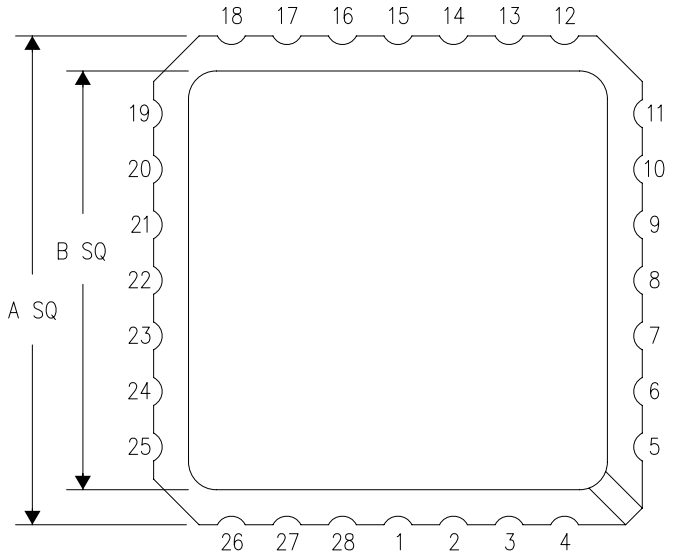


*All dimensions are nominal

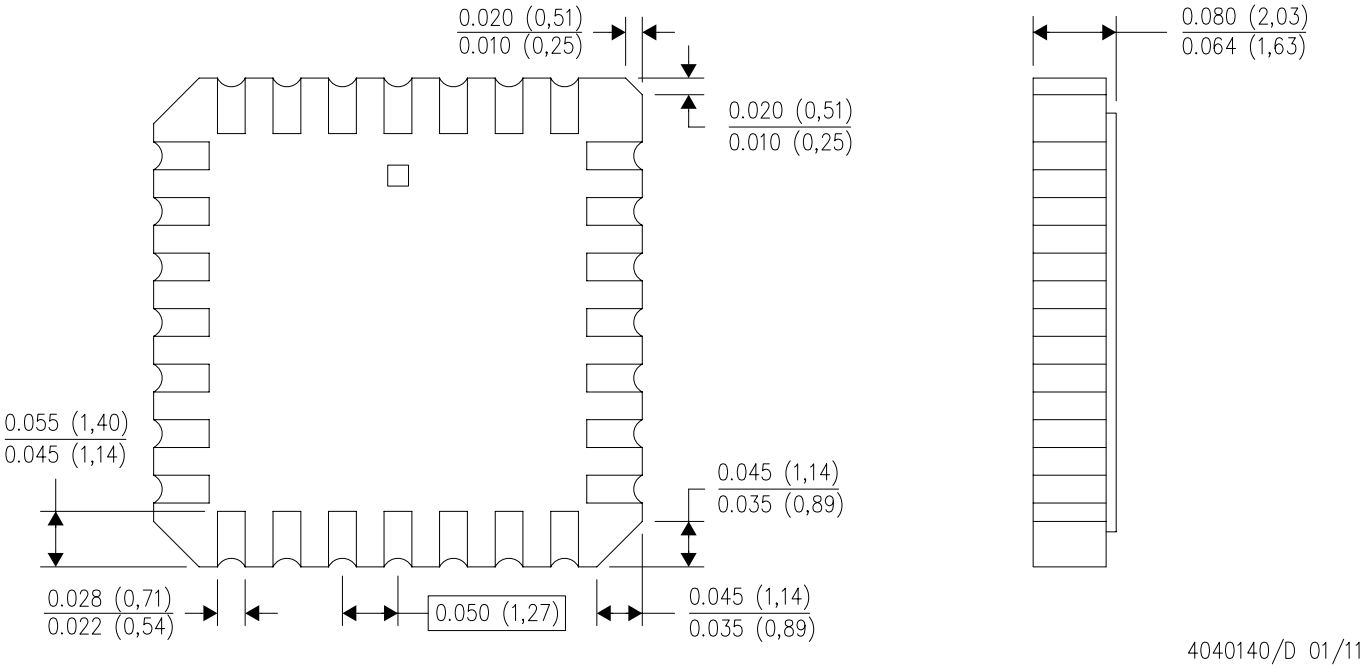
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS390NSR	SO	NS	16	2000	367.0	367.0	38.0
SN74LS393DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74LS393NSR	SO	NS	14	2000	367.0	367.0	38.0

FK (S–CQCC–N**) LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



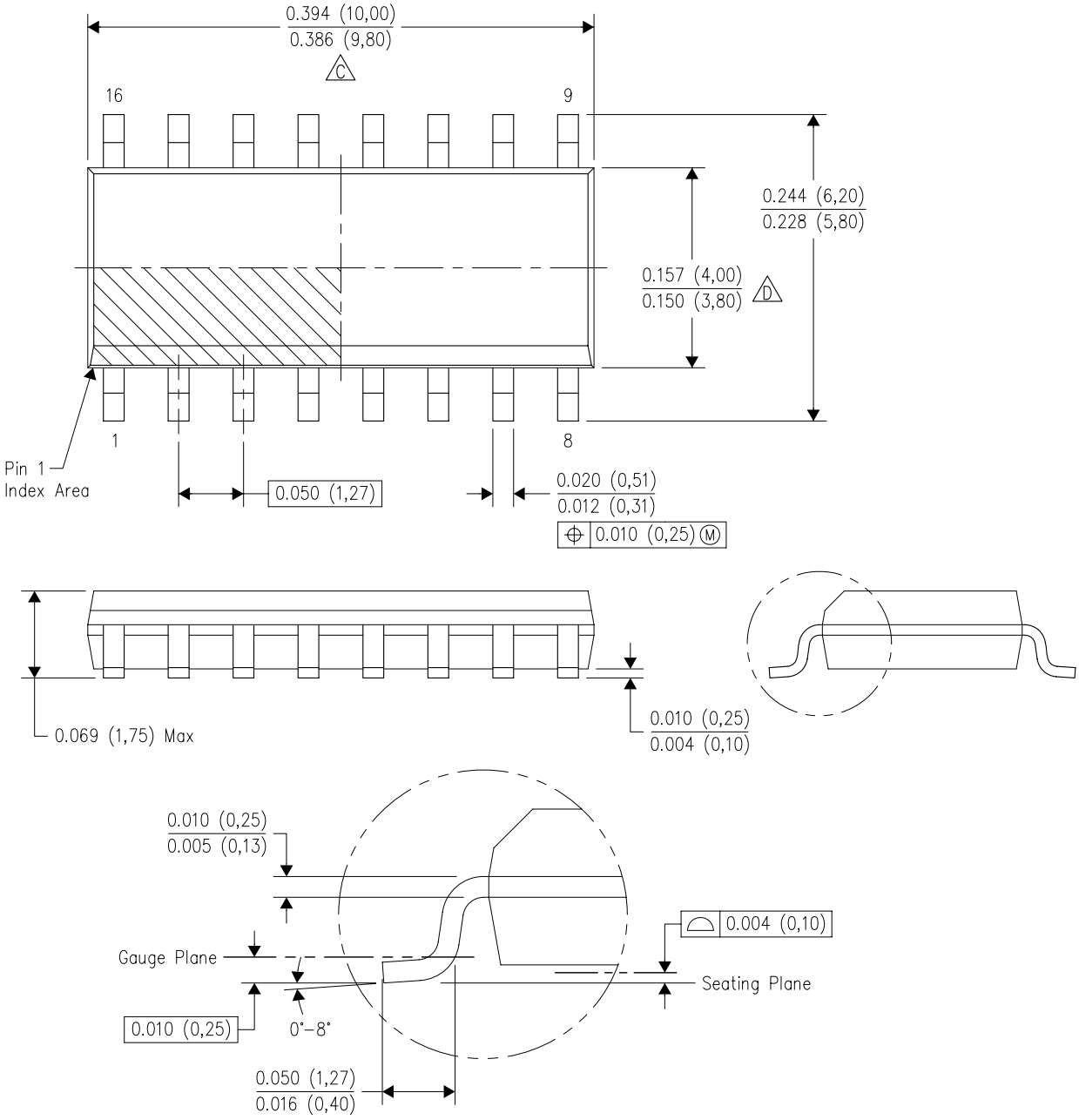
NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

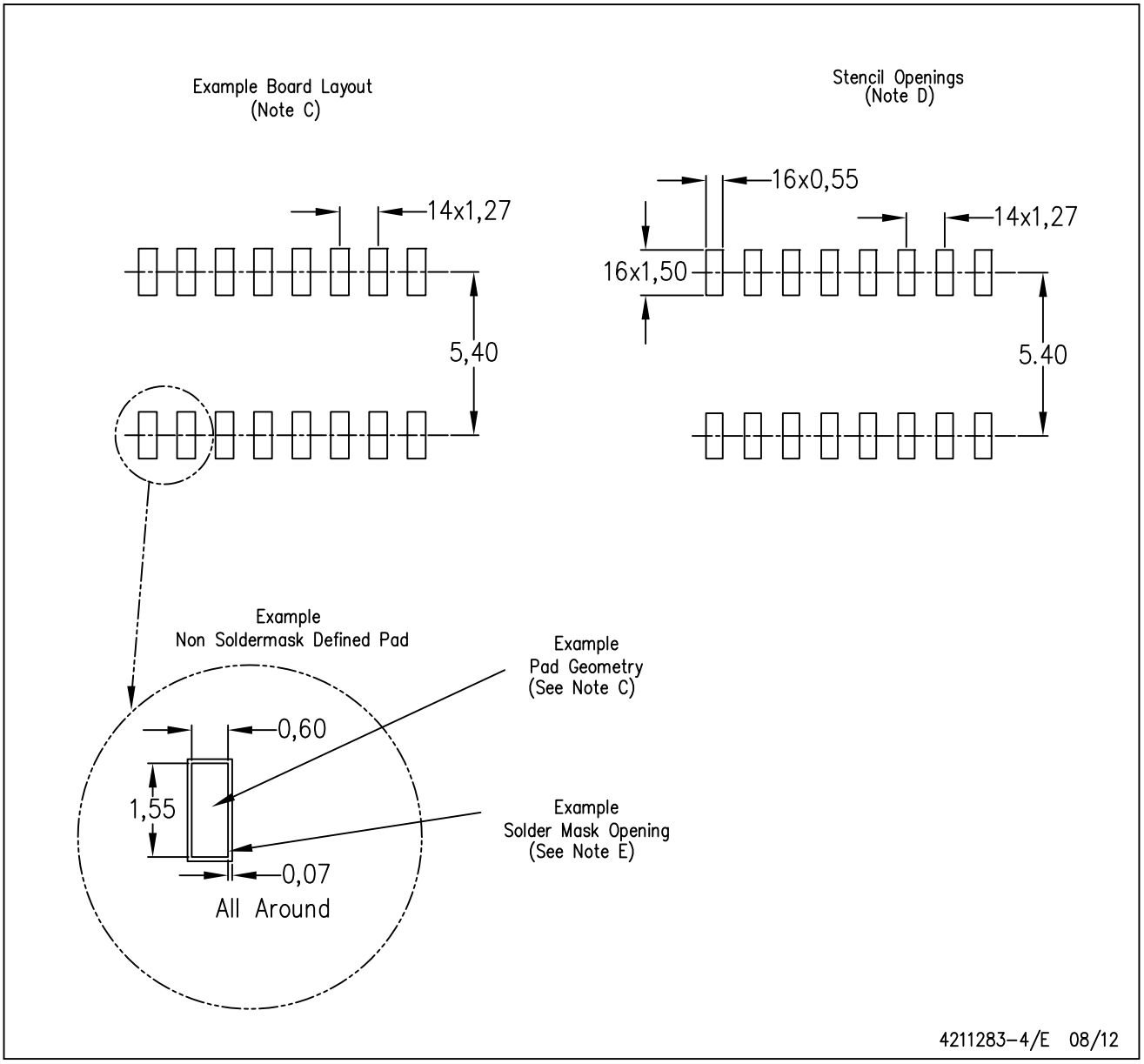
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS–004

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE

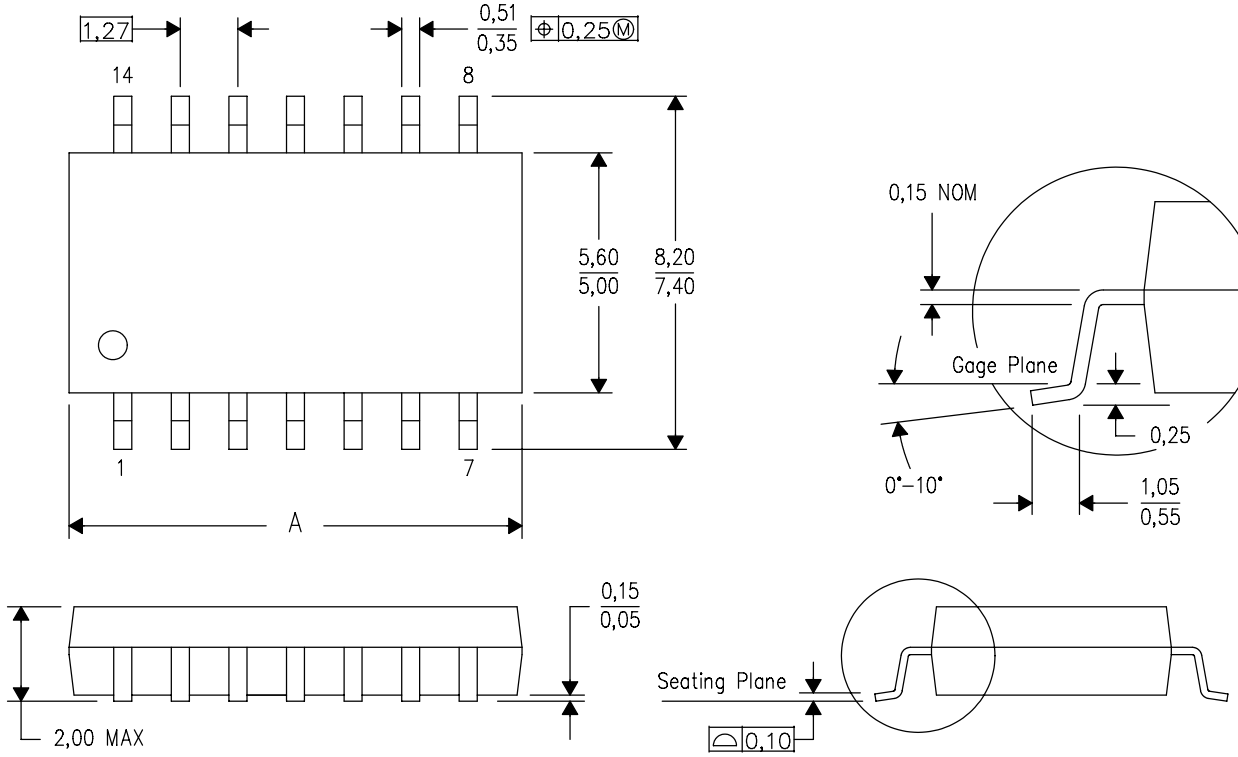


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN

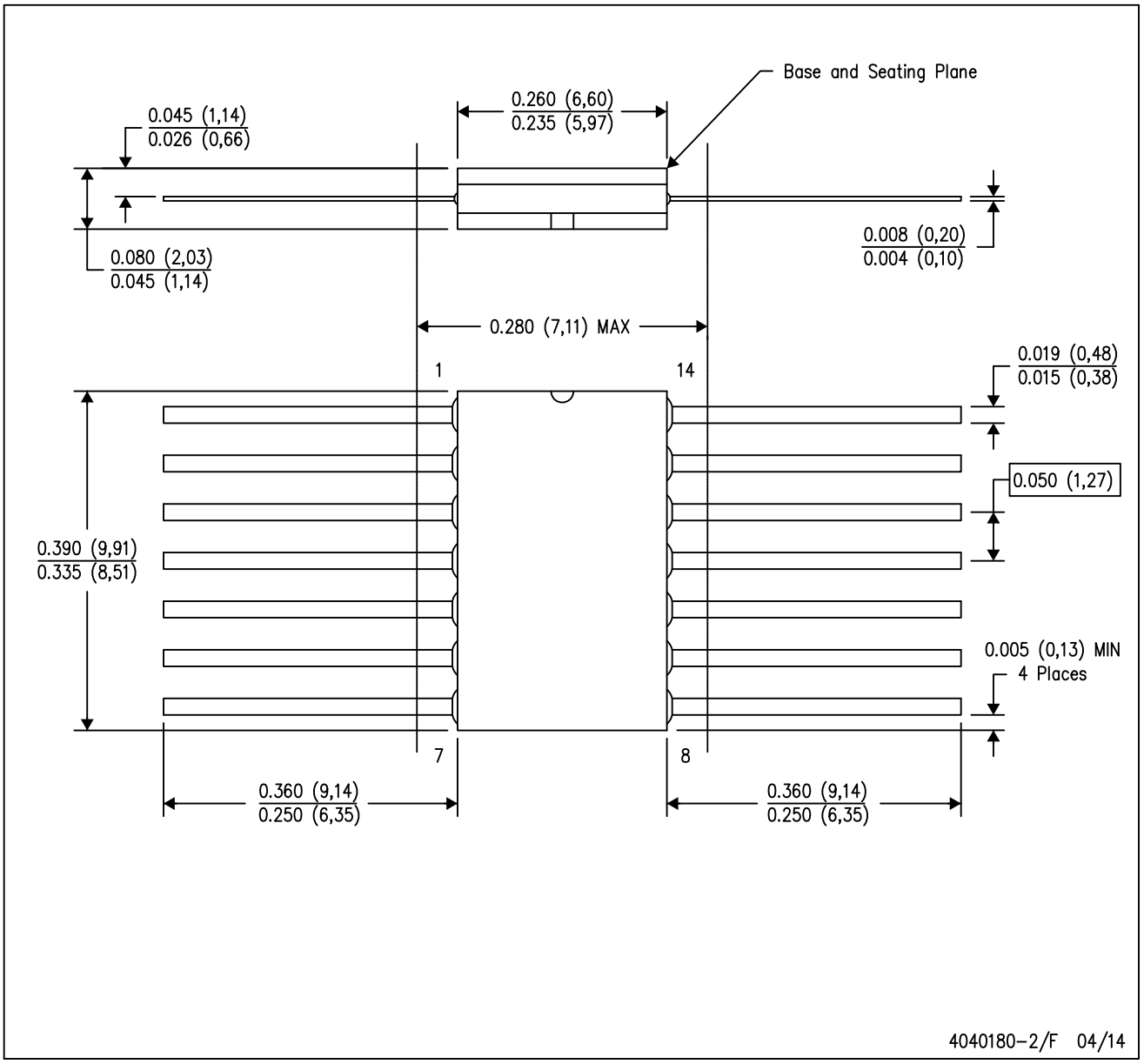


DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

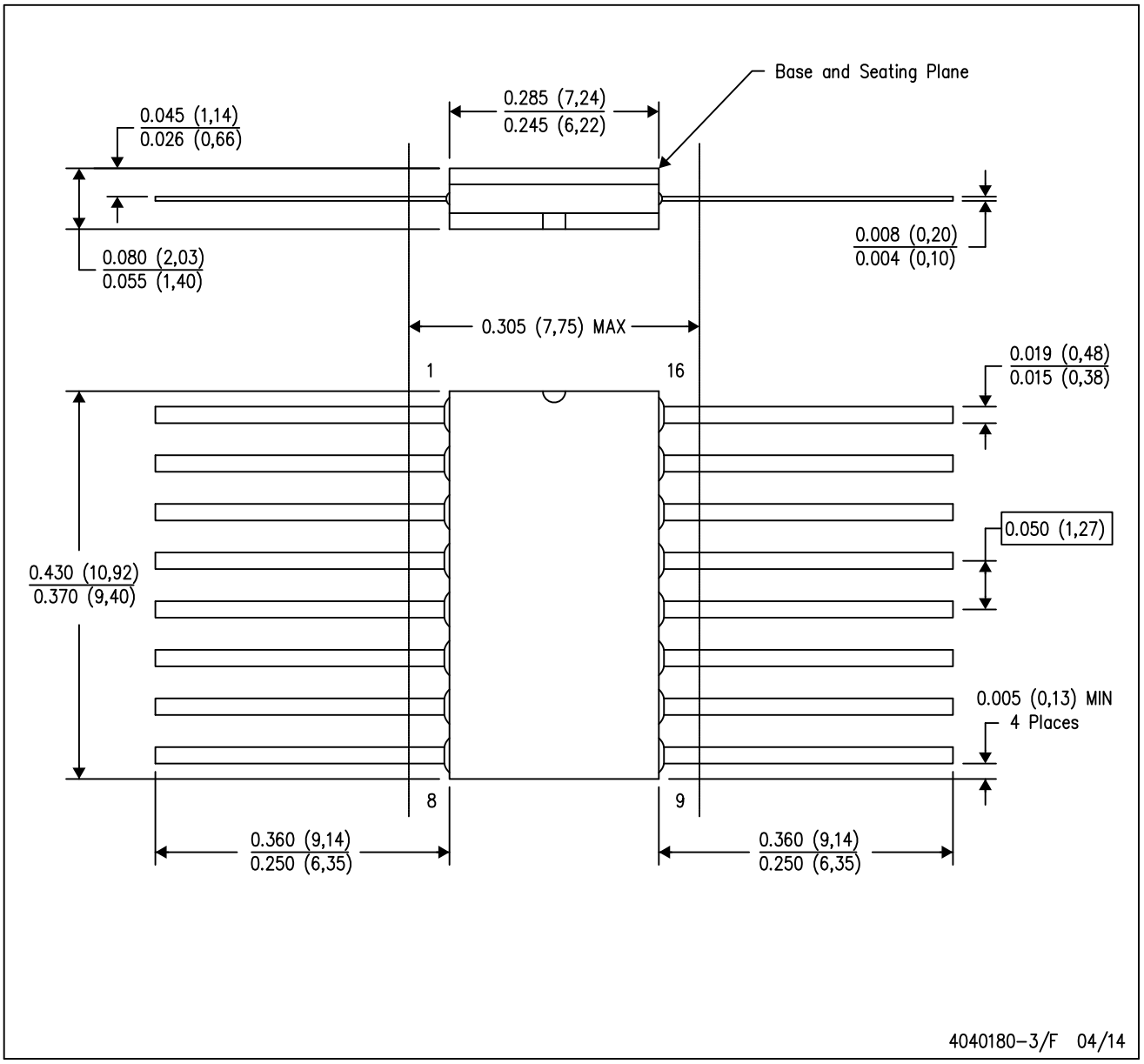
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R–GDFP–F14) CERAMIC DUAL FLATPACK



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14

W (R–GDFP–F16) CERAMIC DUAL FLATPACK

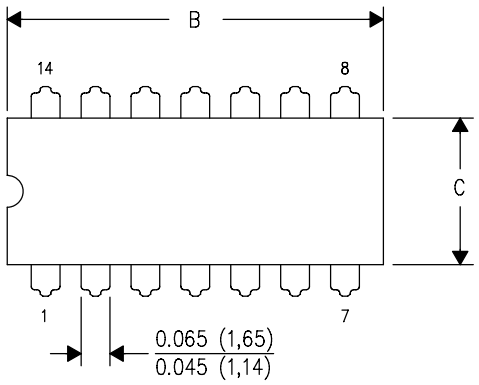


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP2–F16

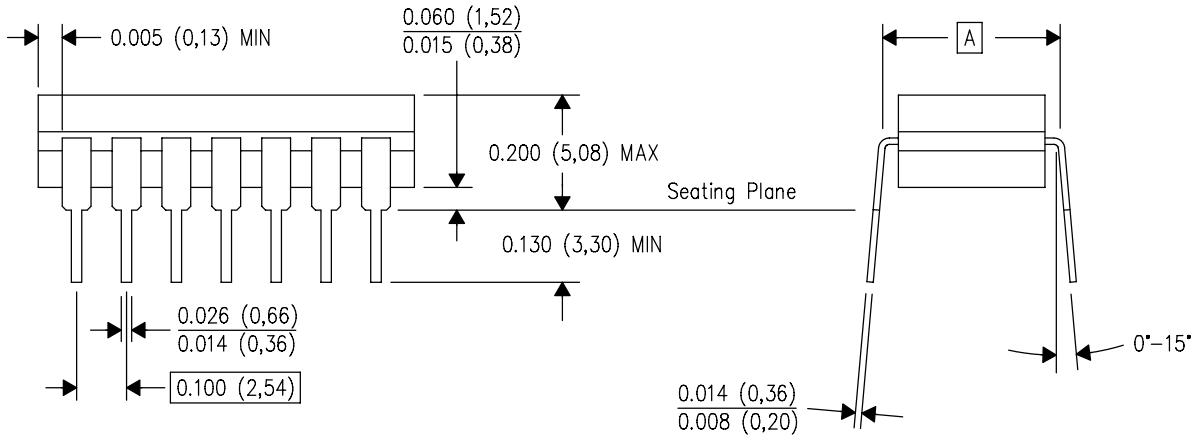
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



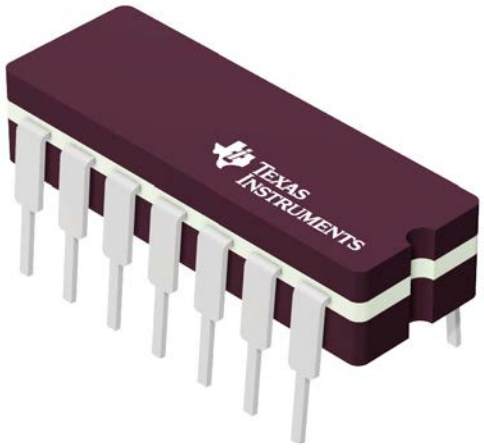
4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

GENERIC PACKAGE VIEW

J 14 CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

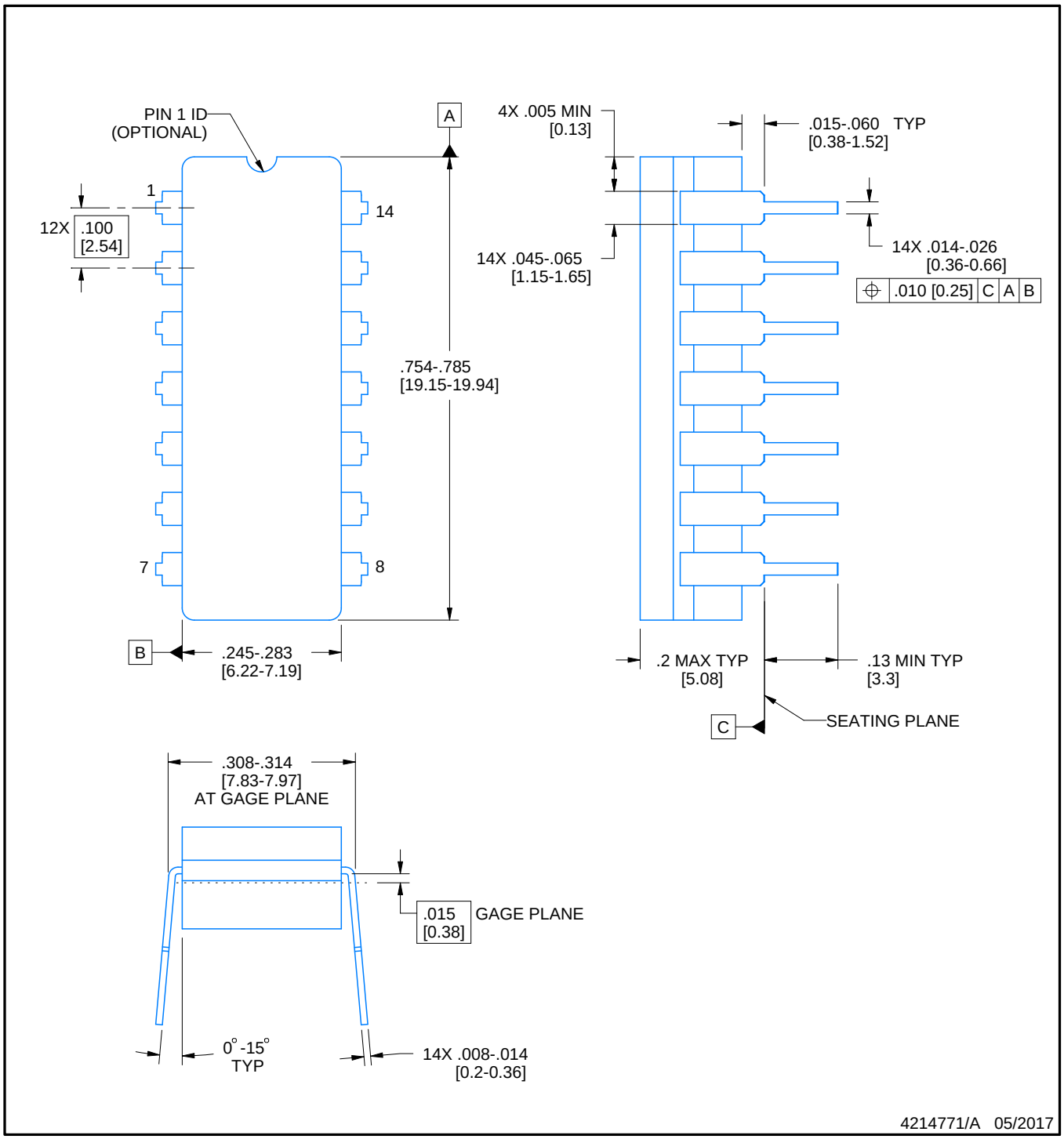
4040083-5/G

PACKAGE OUTLINE

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

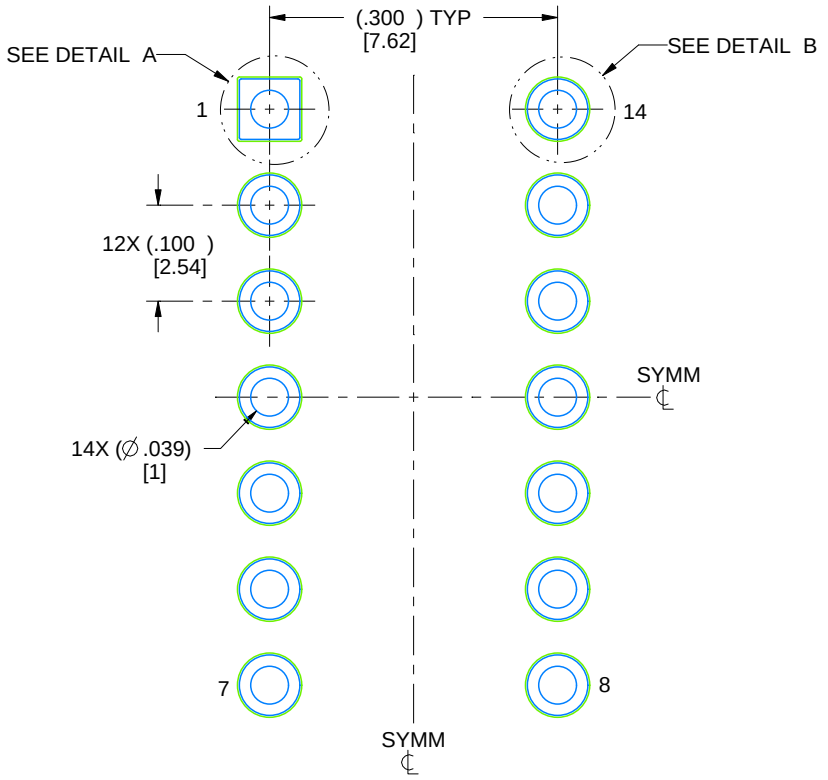
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermitically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

EXAMPLE BOARD LAYOUT

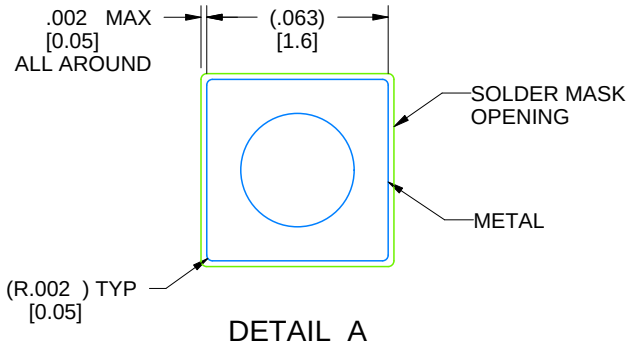
J0014A

CDIP - 5.08 mm max height

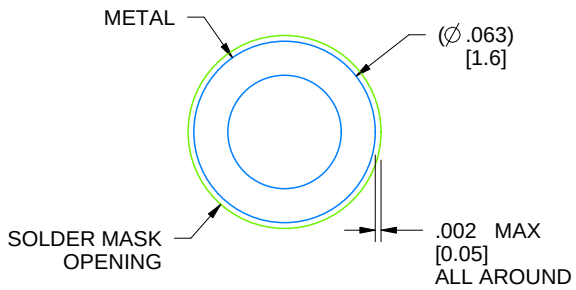
CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X



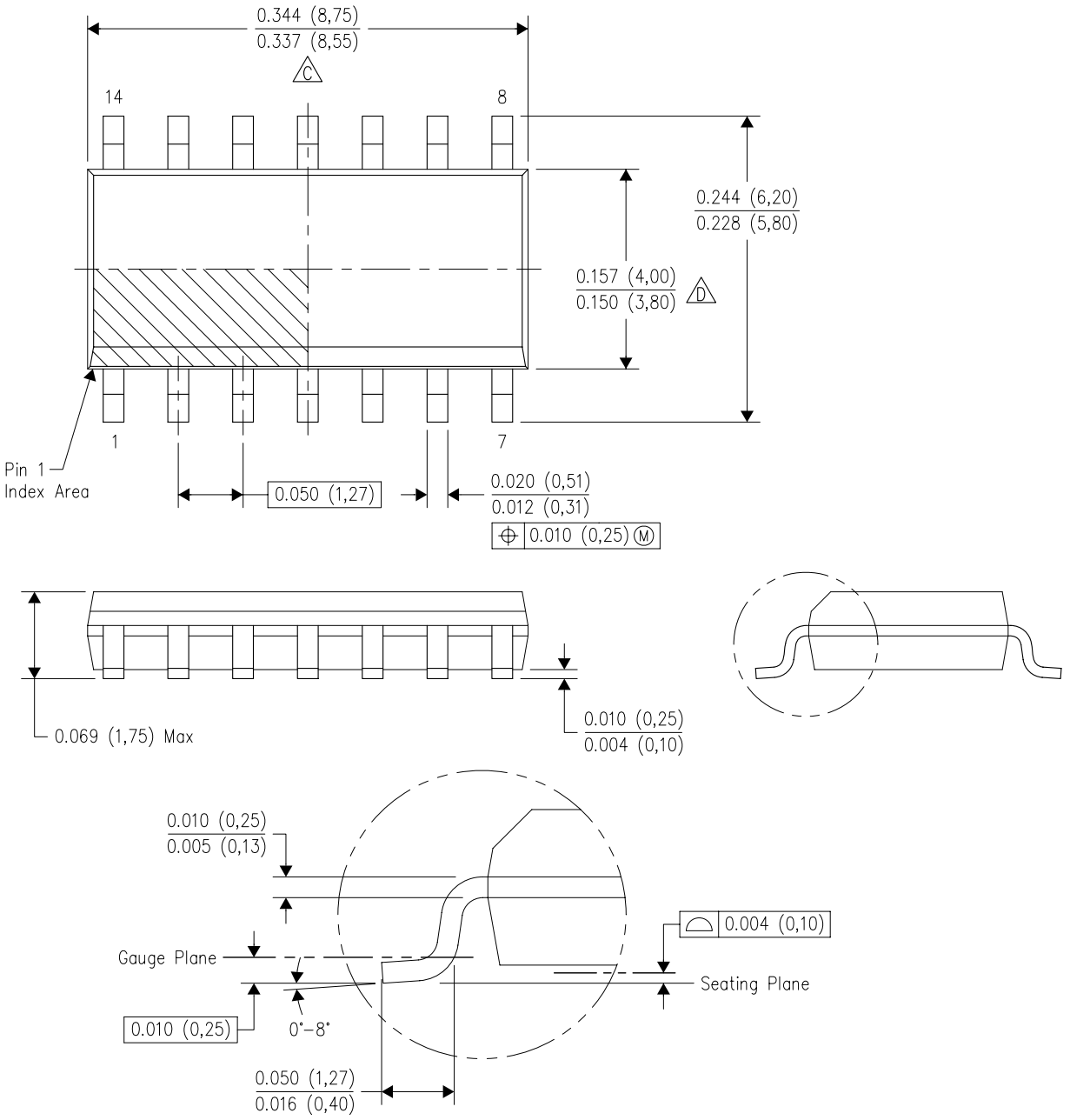
DETAIL A
SCALE: 15X



DETAIL B
13X, SCALE: 15X

4214771/A 05/2017

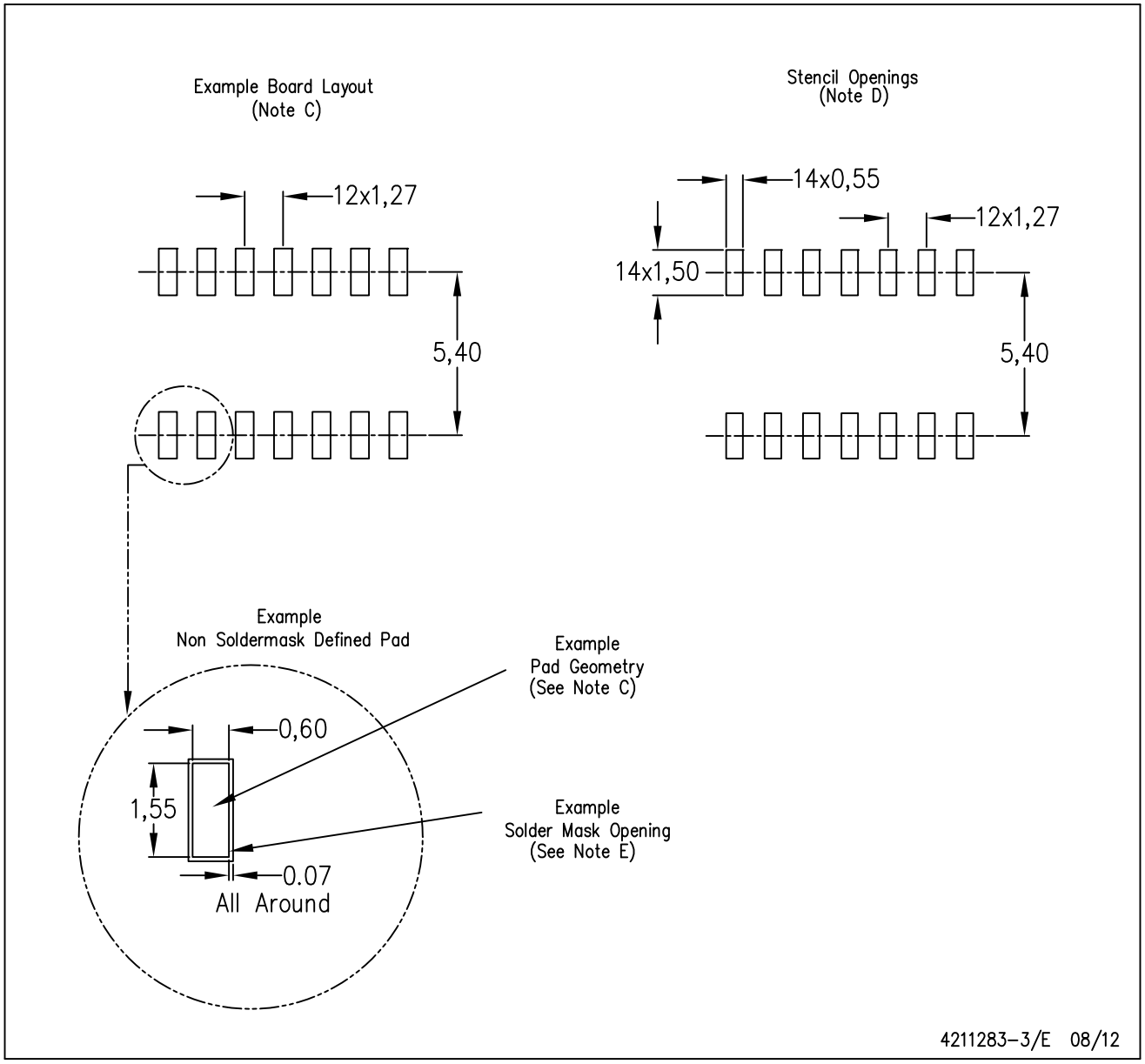
D (R–PDSO–G14) PLASTIC SMALL OUTLINE



4040047–5/M 06/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AB.

D (R–PDSO–G14) PLASTIC SMALL OUTLINE

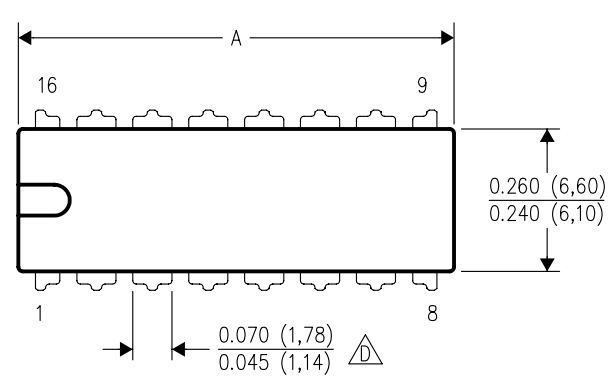


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

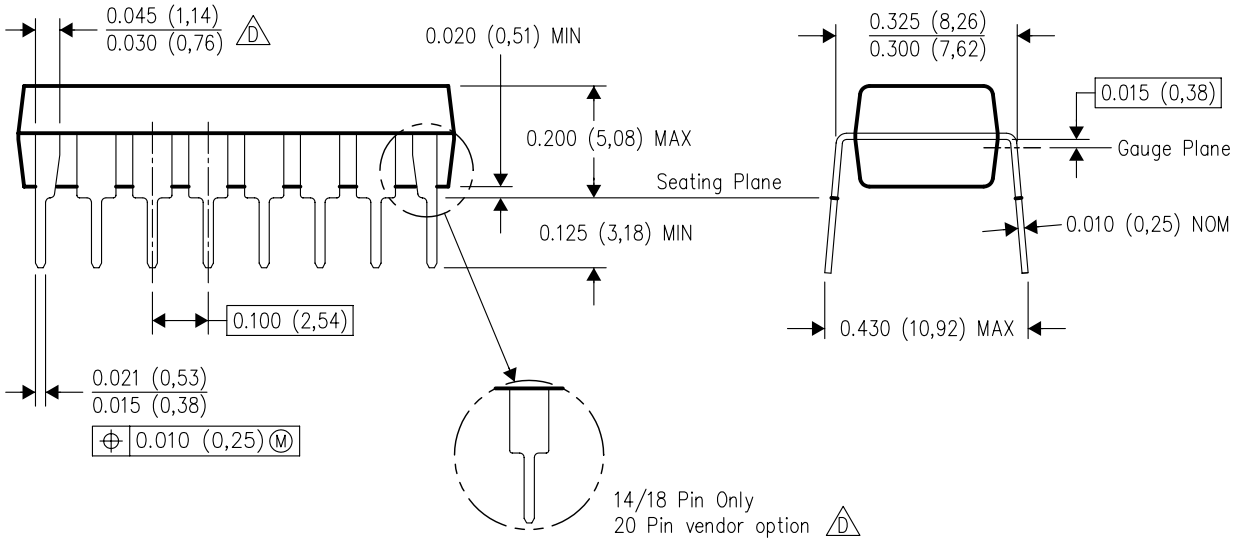
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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